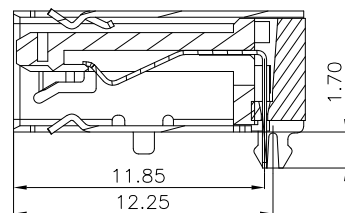
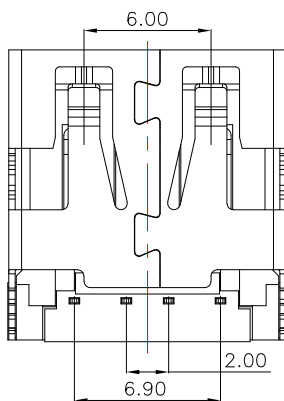
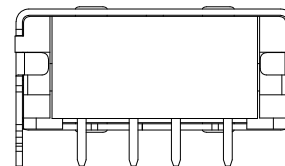
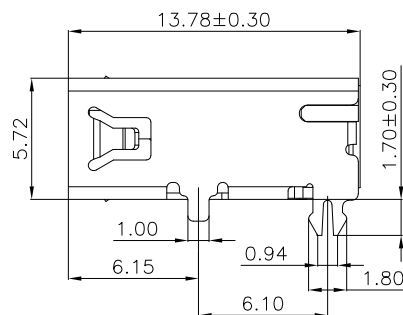
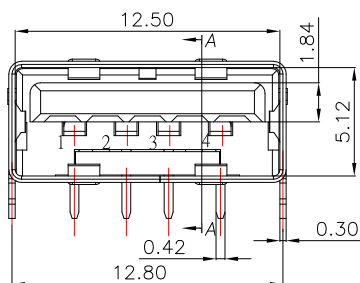
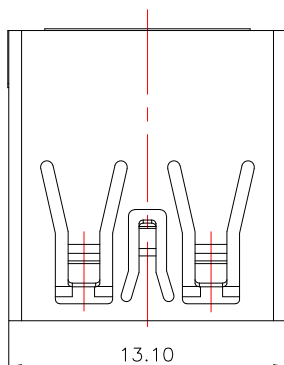


SUA-110H24I-x-S277

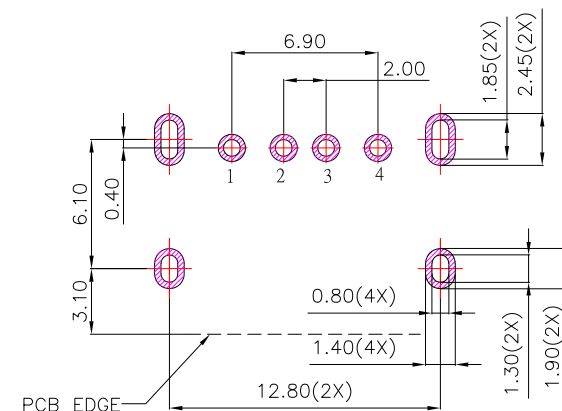
COLOR :

Black: B

White : W



SECTION:A-A



## P.C.B LAYOUT MOUNTING PATTERN

### USB 2.0 PIN ASSIGNMENTS

| Pin # | SIGNAL NAME | DESCRIPTION               |
|-------|-------------|---------------------------|
| 1     | VBUS        | POWER                     |
| 2     | D-          | USB 2.0 DIFFERENTIAL PAIR |
| 3     | D+          |                           |
| 4     | GND         | GROUND FOR POWER RETURN   |
| Shell | Shield      | CONNECTOR METAL SHELL     |

## SPECIFICATIONS

### Electrical:

- 1.Current Rating: 1.8A(VBUS&GND)
- 2.Contact Resistance: 30 mΩ Max
- 3.Dielectric Withstanding Voltage: 100 V AC
- 4.Insulation Resistance: 100 MΩ Min
- 5.Operating Temperature: -25°C ~ 85°C

### Mechanical:

- 1.Connector Mate and Unmate Force  
Mate force: 3.57 kgf (Max)  
Unmate force: 1.02 kgf (Min)

### Material:

- 1.Housing: LCP,UL 94V-0
- 2.Contact: Phosphor Bronze
- 3.Shell: SUS

### Finish:

- 1.Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
- 2.Shell: Nickel under Plated surface layer

| ITEM NO. | DESCRIPTION | DRAWN | DATE   |
|----------|-------------|-------|--------|
| 13       | 新增PIN定義     | Jack  | 091224 |
| 12       | 更新圖面        | Jack  | 052720 |
| 11       | 新增尺寸        | Jack  | 101619 |
| 10       | 更新外型        | Jack  | 010917 |

|                                                              |  |                                     |  |                    |              |       |    |
|--------------------------------------------------------------|--|-------------------------------------|--|--------------------|--------------|-------|----|
| <b>CONTACT</b> 建倚科技股份有限公司<br><b>CONTACT TECHNOLOGY CORP.</b> |  | TOLERANCE UNLESS OTHERWISE STATED : |  | Up to 5 ±0.2       | 3RD. ANGEL'S | UNITS | MM |
|                                                              |  |                                     |  | Above 5 ~ 15 ±0.3  |              |       |    |
|                                                              |  |                                     |  | Above 15 ~ 30 ±0.4 |              |       |    |
|                                                              |  |                                     |  | Above 30 ~ 50 ±0.5 |              |       |    |
|                                                              |  |                                     |  | Angle ±0.3°        |              |       |    |

|              |          |           |          |                                   |
|--------------|----------|-----------|----------|-----------------------------------|
| DRAWN BY:    | DATE     | MAT'L     | TITLE    | CONNECTOR                         |
| Jack Lu      | 09/12/24 |           |          |                                   |
| CHECKED BY:  | DATE     | FINISH    | MODLE    | USB 2.0 A/F DIP 無捲邊, Shell DIP X4 |
| Jacky Chen   | 09/12/24 |           |          |                                   |
| APPROVED BY: | DATE     | SCALE     | DWG NO.  | SUA-110H24I-x-S277                |
| Tony Kao     | 09/12/24 | 1 : 1     |          |                                   |
|              |          | SHEET NO. | PART NO. | SUA-110H24I-x-S277                |
|              |          | 1 of 1    |          |                                   |
|              |          |           |          | SIZE A4                           |
|              |          |           |          | VER R13                           |